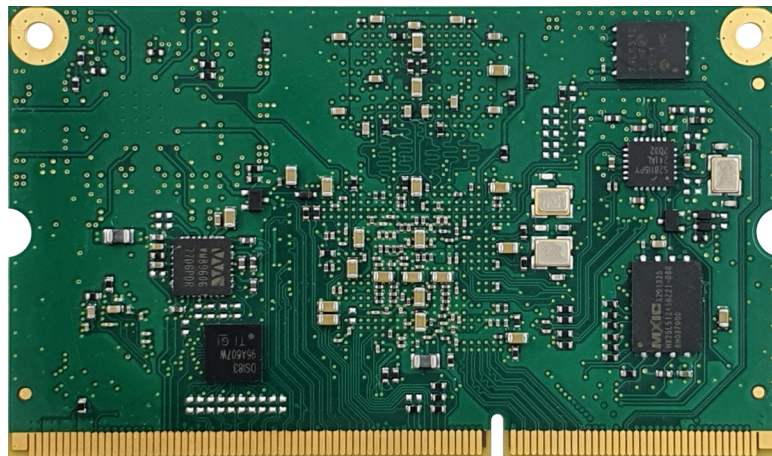
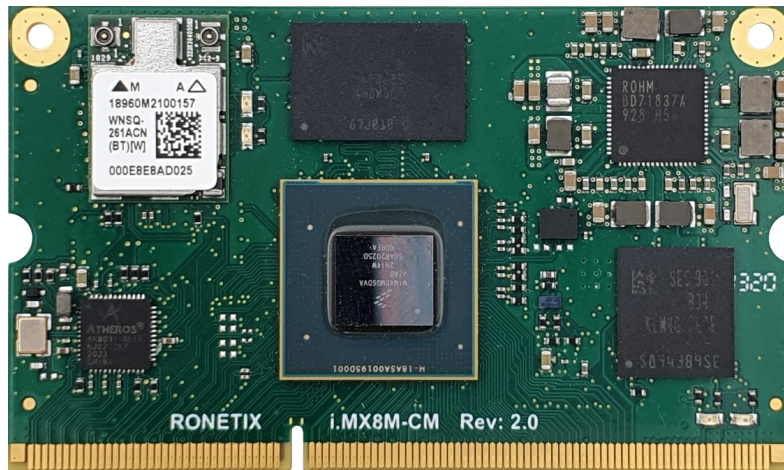


i.MX8M-CM

CPU Module (SoM) with NXP i.MX8MQ

Datasheet

rev 1.0



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1. Document Revision History

Revision	Date	Notes
1.0	01-Jun-2021	Initial release

2. Table of Contents

Table of Contents

1. Document Revision History.....	3
2. Table of Contents.....	3
3. Overview.....	5
3.1 General Information.....	5
3.2 Highlights.....	6
3.3 Block Diagram.....	7
4. CPU Module Hardware Components.....	8
4.1 Power supply.....	8
4.2 CPU i.MX8MQ.....	8
4.2.1 i.MX8MQ Block Diagram.....	9
4.2.2 CPU Platform.....	9
4.3 Memory.....	10
4.3.1 DRAM.....	10
4.3.2 eMMC – non-volatile storage memory.....	10
4.3.3 SPI NOR Flash.....	11
4.3.4 I2C EEPROM.....	11
4.4 Gigabit Ethernet.....	11
4.5 WLAN.....	11
4.6 Audio.....	11
4.7 LVDS bridge.....	12
4.8 LED.....	13
5. SODIMM204 connector.....	13
6. CPU Module interfaces.....	16
6.1 Display interfaces.....	16
6.2 MIPI-CSI Camera interface.....	19
6.3 USB interface.....	20

6.4 PCI-Express.....	21
6.5 MMC, SD, SDIO.....	22
6.6 UART.....	22
6.7 I2C.....	23
6.8 SPI.....	24
6.9 Quad SPI.....	24
6.10 PWM.....	24
6.11 Analog Audio.....	25
6.12 GPIO.....	26
6.13 JTAG.....	26
7. Power Supply.....	26
7.1 Power supply from base board.....	26
7.2 Power supply provided to base board.....	26
7.3 System Signals.....	26
8. Electrical Specifications.....	27
8.1 Absolute maximum ratings.....	27
8.2 Recommended Operating Conditions.....	27
9. Operating Temperature Ranges.....	27
10. Cooling.....	27
11. Mechanical Drawings.....	28
11.1 Base board mounting.....	28
11.2 Standoffs.....	28
12. Warranty Terms.....	29

3. Overview

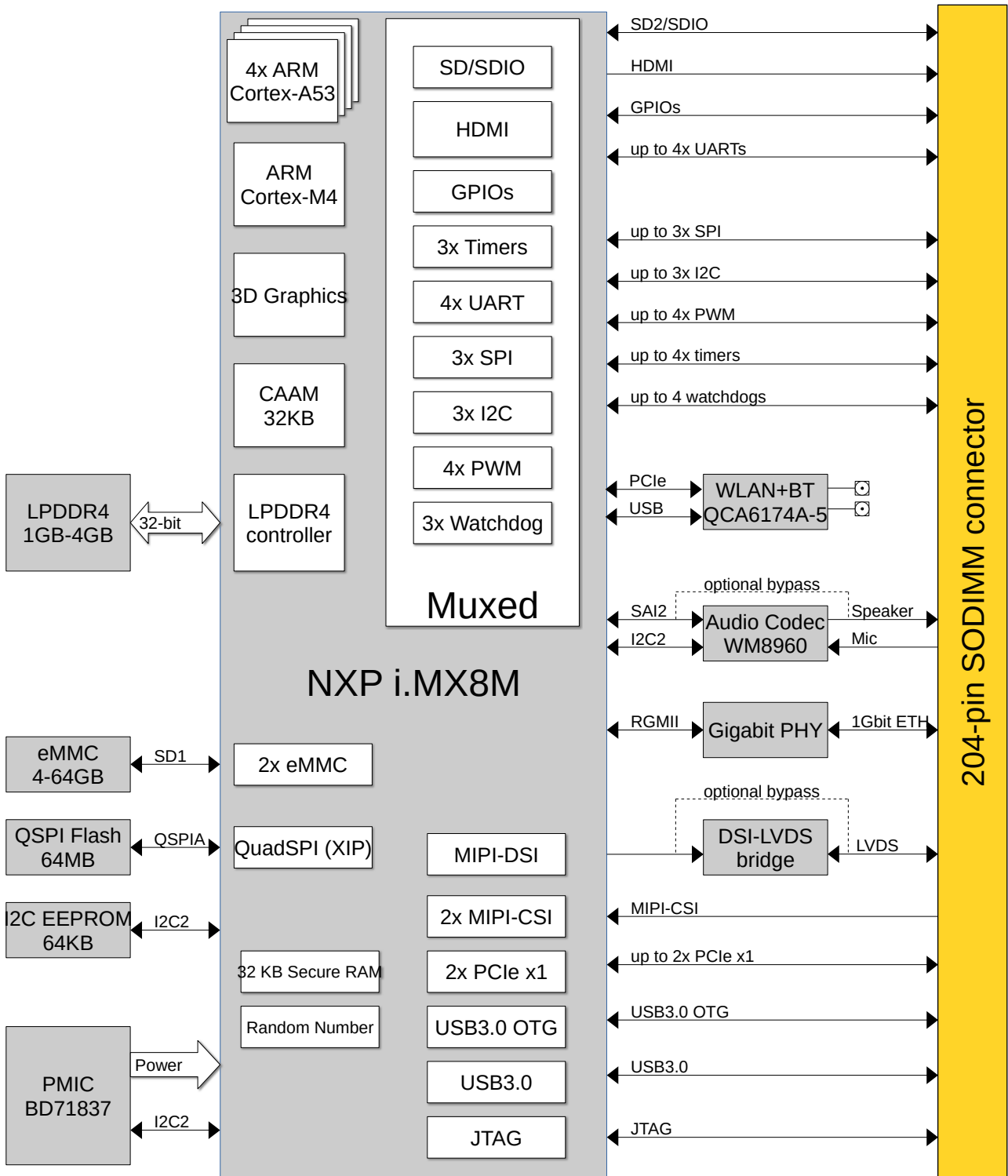
3.1 General Information

The **i.MX8M-CM** is a high-performance processing for low-power CPU Module (SoM – System On Module) that perfectly fits various embedded products of connected and portable devices. It is based on the NXP i.MX8MQ family of multipurpose processors from which feature an ARM® Cortex™-A53 up to 1.5GHz + an additional ARM Cortex-M4. This Heterogeneous Multicore Processing architecture enables the device to run an open operating system like Linux on the Cortex-A53 core and an RTOS like FreeRTOS™ on the Cortex-M4 core for time and security critical tasks.

3.2 Highlights

CPU	<ul style="list-style-type: none">• Quad Armv8-A, 64-bit Cortex™-A53 Core, 1.5GHz• ARM® Cortex™-M4, 266MHz
Memory	<ul style="list-style-type: none">• RAM: 1 GiB LPDDR4 (optional: up to 4 GiB)• eMMC: 4 GiB (optional: up to 64 GiB)• I2C EEPROM: 64KiB (optional)• QSPI NOR Flash: 64 MiB (optional)
Display	<ul style="list-style-type: none">• HDMI• LVDS, up to 1400 x 1050 @60Hz• MIPI DSI
Camera	<ul style="list-style-type: none">• 2x MIPI-CSI, 4 data lanes
Network	<ul style="list-style-type: none">• Ethernet: 10/100/1000Mbps• WiFi: Atheros QCA6174A-5, 802.11ac, dual band 2×2 MIMO (optional)• Bluetooth: Bluetooth 5.0 Secure Connection Compliant (optional)
Audio	<ul style="list-style-type: none">• Audio codec WM8960: Stereo Headphone, Stereo Class D Speaker 1W, Microphone
I/O	<ul style="list-style-type: none">• 2x PCIe 2.0, 1-lane each• 2x USB3.0/2.0 OTG port• Up to 4x UART ports• MMC/SD/SDIO• Up to 3x SPI• Up to 3x I2C• Up to 4x general purpose PWM signals• GPIOs
Electrical	<ul style="list-style-type: none">• Supply Voltage: 3.5 – 4.5V
Physical	<ul style="list-style-type: none">• Board size: 67x40mm• SO-DIMM 200 JEDEC MO-274 module (67.6x40mm)• Operation temperature: 0° +70°C, -20° to 85° C (optional)• Relative humidity: 10% to 90%• MTTF > 200000 hours

3.3 Block Diagram



4. CPU Module Hardware Components

This chapter describes the hardware components of i.MX8M-CM SoM.

4.1 Power supply

i.MX8M-CM uses Rohm's BD71837 as a Power Management Integrated circuit (PMIC) designed specifically for use with NXP's i.MX8M series of application processors. The PMIC regulates all power rails required on CPU module from a single 3.8V-5.0V power supply.

The PMIC is fully programmable via the I2C interface and associated register map. Additional communication is provided by direct logic interfacing including interrupt, watchdog and reset.

4.2 CPU i.MX8MQ

The i.MX 8M Dual / 8M Quad processors represent NXP's latest market of connected streaming audio/video devices, scanning/imaging devices, and various devices requiring high-performance, low-power processors. The i.MX 8M Dual / 8M Quad processors feature advanced implementation of a quad Arm®Cortex®-A53 core, which operates at speeds of up to 1.5 GHz. A general purpose Cortex®-M4 core processor is for low-power processing. The DRAM controller supports 32-bit/16-bit LPDDR4, DDR4, and DDR3L memory. There are a number of other interfaces for connecting peripherals, such as WLAN, Bluetooth, GPS, displays, and camera sensors.

4.2.1 Block Diagram

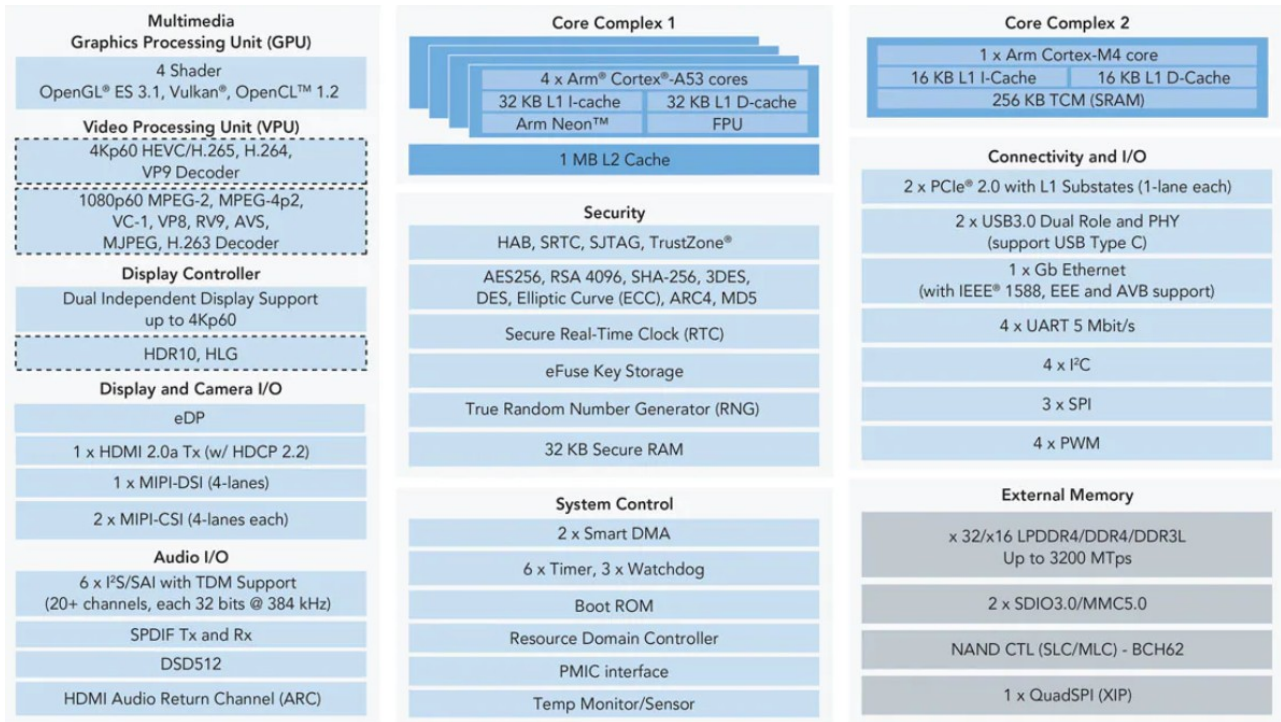


Figure 4.1: iMX8M Block Diagram

4.2.2 CPU Platform

The i.MX8M Quad processor implements four ARM® Cortex®-A53 cores intended for high level O/S, with an ARM® Cortex®-M4 core dedicated for real-time tasks.

The ARM Cortex-A53 MPCore™ platform has the following features:

- Quad ARM Cortex-A53 Cores
- Target frequency of 1.5GHz
- The core configuration is symmetric, where each core includes:
 - 32 KByte L1 Instruction Cache
 - 32 KByte L1 Data Cache
 - MPE (media processing engine) with NEON co-processor supporting SIMD architecture
- The Arm Cortex-A53 Core complex shares:

- General interrupt controller (GIC) with 128 interrupt support
- Global timer
- Snoop control unit (SCU)
- 1 MB unified I/D L2 cache
- NEON MPE co-processor
 - SIMD Media Processing Architecture
 - NEON register file with 32x64-bit general-purpose registers
 - NEON Integer execute pipeline (ALU, Shift, MAC)
 - NEON dual, single-precision floating point execute pipeline (FADD, FMUL)
 - NEON load/store and permute pipeline

The ARM Cortex-M4 platform includes the following features:

- Cortex-M4 CPU core operating at 266 MHz
- MPU (memory protection unit)
- FPU (floating-point unit)
- 16 KByte instruction cache
- 16 KByte data cache
- 256 KByte TCM (tightly-coupled memory)

4.3 Memory

4.3.1 DRAM

i.MX8M-CM is standard equipped with 1 GB LPDDR4 memory. Optionally up to 4 GB can be assembled. The data bus is 32-bit wide.

4.3.2 eMMC – non-volatile storage memory

i.MX8M-CM is standard equipped with 4 GB eMMC. Optionally up to 32 GB can be assembled.

The eMMC can be used as boot device.

4.3.3 SPI NOR Flash

i.MX8M-CM can be assembled with a QSPI NOR Flash.

4.3.4 I2C EEPROM

i.MX8M-CM can be assembled with a I2C EEPROM.

4.4 Gigabit Ethernet

i.MX8M-CM implements one full-featured 10/100/1000 Ethernet ports implemented with MAC built into the i.MX8M SoC, coupled with AR8031 RGMII Ethernet PHYs from Qualcomm. The Ethernet interface support the following main features:

- 10/100/1000 BASE-T IEEE 802.3 compliant.
- IEEE 802.3u compliant Auto-Negotiation.
- Supports all IEEE 1588 frames - inside the MAC.
- Automatic channel swap (ACS).
- Automatic MDI/MDIX crossover.
- Automatic polarity correction.
- Activity and speed indicator LED controls.

4.5 WLAN

i.MX8M-CM optional wireless communication is implemented with SparkLAN WNSQ-261ACN(BT) WLAN module. WNSQ-261ACN(BT) is an 802.11ac/b/g/n Dual-Band Wi-Fi+Bluetooth M.2 LGA type 1216 module based on Qualcomm Atheros QCA6174A-5 chipset. It is Dual-Band AC on 2.4GHz + 5GHz and incorporates the latest Bluetooth 5.0. The download speed are 300Mbps on N networks and 867Mbps on AC network.

i.MX8M-CM is equipped with two U.FL high frequency connectors for external antennas.

4.6 Audio

i.MX8M-CM implements an audio codec WM8960 (assembled optional) . The WM8960 is a low power stereo codec featuring Class D speaker drivers to provide 1W per channel into 8Ω loads. External component requirements are drastically reduced as no separate microphone, speaker or headphone amplifiers are required. Advanced on-chip digital signal processing performs automatic level control for the microphone or line input. Stereo 24-bit Delta Sigma converters are used with low power over-sampling digital interpolation and decimation filters and a flexible digital audio

interface. The main clock can be input directly or generated internally by an onboard PLL, supporting most commonly used clocking schemes.

The WM8960 supports the following features:

- Stereo class D speaker driver, 1W per channel
- On-chip headphone driver 40mW output power into 16Ω
- Microphone interface
- Pop and click suppression
- DAC SNR 98 dB ('A' weighted), THD -84 dB at 48 kHz, 3.3V
- ADC SNR 95 dB ('A' weighted), THD -82 dB at 48 kHz, 3.3V
- Programmable ALC / limiter and noise gate

Please refer to the WM8960 datasheet for additional details.

4.7 LVDS bridge

i.MX8M-CM implements (optional) onboard LVDS display interface by converting the MIPI-DSI to LVDS signals using Texas Instruments SN65DSI83 transceiver. The SN65DSI83 DSI to FlatLink bridge device features a single-channel MIPI D-PHY receiver front-end configuration with four lanes per channel operating at 1 Gbps per lane; a maximum input bandwidth of 4 Gbps. The bridge decodes MIPI DSI18 bpp RGB666 and 24 bpp RGB888 packets and converts the formatted video data stream to a FlatLink-compatible LVDS output operating at pixel clocks operating from 25 MHz to 154 MHz, offering a Single-Link LVDS with four data lanes per link. The SN65DSI83 device can support up to WUXGA1920 × 1200 at 60 frames per second, at 24 bpp with reduced blanking. The SN65DSI83 device is also suitable for applications using 60 fps 1366 × 768 /1280 × 800 at 18 bpp and 24 bpp. Partial line buffering is implemented to accommodate the data stream mismatch between the DSI and LVDS interfaces. Designed with industry-compliant interface technology, the SN65DSI83 device is compatible with a wide range of microprocessors, and is designed with a range of power management features including low-swing LVDS outputs, and the MIPI defined ultra-low power state (ULPS) support.

Main features:

- LVDS Output Clock Range of 25 MHz to 154MHz.
- Suitable for up to 60 fps WUXGA 1920 x 1080 at 18 bpp and 24 bpp Color with Reduced Blanking

- ESD Rating ± 2 kV

4.8 LED

The i.MX8M-CM features a green LED controlled by GPIO4_IO28 signal of the i.MX8M. The LED is ON when GPIO4_IO28 is logic Low.

5. SODIMM204 connector

The i.MX8M-CM exposes a 204 pin SO-DIMM connector.

Recommended mating Connector socket for custom board interfacing are the following connectors (or equivalent):

- TE Connectivity 2013289-2 or 2013289-1
- Cvilux CS69-2042CA0-R0
- JAE MM80-204B1-1

SODIMM Pin	Signal	i.MX8M Ball	Alt-0	Alt-1	Alt-2	Alt-3	Alt-4	Alt-5
1	ETH1_TX1_P							
3	ETH1_TX1_N							
5	ETH1_RX1_P							
7	ETH1_RX1_N							
9	ETH1_TX2_P							
11	ETH1_TX2_N							
13	ETH1_RX2_P							
15	ETH1_RX2_N							
17	ETH1_LED_ACT							
19	ETH1_LED_LINK100							
21	SD2_nCD	L21	usdhc2.CD_B					gpio2.IO[12]
23	ETH1_LED_LINK1000							
25	GPIO3_IO14	M20	rawnand_DQS	qspl.B_DATA[3]				gpio3.IO[14]
27	GPIO3_IO12	L19	rawnand_DATA06	qspl.B_DATA[1]				gpio3.IO[12]
29	CN_PCIE1_REF_CLK_P	K25						
31	CN_PCIE1_REF_CLK_N	K24						
33	CN_PCIE1_TX_P	J25						
35	CN_PCIE1_TX_N	J24						
37	CN_PCIE1_RX_P	H25						
39	CN_PCIE1_RX_N	H24						
41	PCIE2_REF_CLK_N	F24						
43	PCIE2_REF_CLK_P	F25						
45	PCIE2_TX_N	E24						
47	PCIE2_TX_P	E25						
49	PCIE2_RX_N	D24						
51	PCIE2_RX_P	D25						
53	CSI1_D0_P	B23						
55	CSI1_D0_N	A23						
57	CSI1_CLK_P	B22						
59	CSI1_CLK_N	A22						
61	CSI2_D2_P	B21						
63	CSI2_D2_N	A21						
65	CSI2_D1_P	B20						
67	CSI2_D1_N	A20						
69	CSI2_CLK_P	B19						
71	CSI2_CLK_N	A19						
73	USB1_VBUS	D14						
75	USB1_ID	C14						
77	USB1_D_P	A14						
79	USB1_D_N	B14						
81	USB1_TX_P	A13						
83	USB1_TX_N	B13						
85	USB1_RX_P	A12						
87	USB1_RX_N	B12						
89	USB2_D_P	A10						
91	USB2_D_N	B10						
93	USB2_TX_P	A9						
95	USB2_TX_N	B9						
97	USB2_RX_P	A8						
99	USB2_RX_N	B8						
101	USB2_VBUS	D9						
103	USB2_ID	C9						
105	PCIE2_nCLKREQ	F9	i2c4.SDA	pwm1.OUT				gpio5.IO[21]
107	UART1_TXD	A7	uart1_TX	ecspi3.MOSI				gpio5.IO[23]
109	UART3_TXD	B7	uart3_TX	uart1.RTS_B				gpio5.IO[27]
111	UART3_RXD	A6	uart3_RX	uart1.CTS_B				gpio5.IO[26]
113	UART2_RXD	B6	uart2_RX	ecspi3.MISO				gpio5.IO[24]
115	ECSP12_SS0	A5	ecspi2_SS0	uart4.RTS_B				gpio5.IO[13]
117	ECSP12_MISO	B5	ecspi2_MISO	uart4.CTS_B				gpio5.IO[12]
119	ECSP11_MOSI	A4	ecspi1_MOSI	uart3_TX				gpio5.IO[7]
121	UART3_CTS	B4	ecspi1_MISO	uart3.CTS_B				gpio5.IO[8]
123	SAI1_MCLK	A3	sai1_MCLK	sai5.MCLK				gpio4.IO[20]
125	SAI1_TXD6	B3	sai1_TX_DATA[0]	sai6.RX_SYNC			coresight.TRACE[15]	gpio4.IO[18]
127	SAI1_TXD2	B2	sai1_TX_DATA[2]	sai5_TX_DATA[2]			coresight.TRACE[11]	gpio4.IO[14]
129	SAI1_TXD5	C2	sai1_TX_DATA[5]	sai6_RX_DATA[0]	sai6_TX_SYNC		coresight.TRACE[14]	gpio4.IO[17]
131	SAI1_TXD7	C1	sai1_TX_DATA[7]	sai6.MCLK	sai1_TX_BCLK			gpio4.IO[19]
133	SAI1_TXD4	D2	sai1_TX_DATA[4]	sai6_RX_BCLK	sai6_TX_DATA[0]		coresight.TRACE[13]	gpio4.IO[16]
135	SAI1_TXD3	D1	sai1_TX_DATA[3]	sai5_TX_DATA[3]	sai6_TX_BCLK		coresight.TRACE[12]	gpio4.IO[15]
137	SAI1_TXD1	E2	sai1_TX_DATA[1]	sai5_TX_DATA[1]			coresight.TRACE[10]	gpio4.IO[13]
139	SAI1_TXC	E1	sai1_TX_BCLK	sai5_TX_BCLK			coresight.TRACE[9]	gpio4.IO[11]
141	SAI1_TXD0	F2	sai1_TX_DATA[0]	sai5_TX_DATA[0]			coresight.TRACE[8]	gpio4.IO[12]
143	SAI1_RXD5	F1	sai1_RX_DATA[0]	sai6_TX_DATA[0]	sai6_RX_SYNC		coresight.TRACE[6]	gpio4.IO[7]
145	SAI1_RXD6	G2	sai1_RX_DATA[0]	sai6_TX_SYNC	sai1_TX_SYNC	sai1_TX_DATA[4]	coresight.TRACE[7]	gpio4.IO[8]
147	SAI1_RXD7	G1	sai1_RX_DATA[7]	sai6.MCLK			coresight.EVENT0	gpio4.IO[9]
149	SAI1_RXD2	H2	sai1_RX_DATA[2]	sai5_RX_DATA[2]			coresight.TRACE[3]	gpio4.IO[4]
151	SAI1_TXFS	H1	sai1_TX_SYNC	sai5_TX_SYNC			coresight.EVENT1	gpio4.IO[10]
153	SAI1_RXD3	J2	sai1_RX_DATA[3]	sai5_RX_DATA[3]	sai6_RX_BCLK		coresight.TRACE[4]	gpio4.IO[5]
155	SAI1_RXD4	J1	sai1_RX_DATA[4]	sai5_TX_BCLK	sai6_RX_DATA[0]	sai1_RX_SYNC	coresight.TRACE[5]	gpio4.IO[6]
157	SAI1_RXD0	K2	sai1_RX_DATA[0]	sai5_RX_DATA[0]			coresight.TRACE[1]	gpio4.IO[2]
159	SAI1_RXC	K1	sai1_RX_BCLK	sai5_RX_BCLK			coresight.TRACE[0]	gpio4.IO[1]
161	SAI1_RXD1	L2	sai5_RX_DATA[1]	sai1_TX_DATA[3]	sai1_TX_SYNC	sai5_TX_BCLK		gpio3.IO[22]
163	SAI1_RXFS	L1	sai5_RX_SYNC	sai1_TX_DATA[0]				gpio3.IO[19]
165	MIC							
167	GND							
169	UART1_RXD	C7	uart1_RX	ecspi3.SCLK				gpio5.IO[22]
171	UART2_TXD	D6	uart2_TX	ecspi3_SS0				gpio5.IO[25]
173	ECSP11_SCLK	D5	ecspi1_SCLK	uart3.RX				gpio5.IO[6]
175	ECSP12_SCLK	C5	ecspi2_SCLK	uart4.RX				gpio5.IO[10]
177	ECSP12_MOSI	E5	ecspi2_MOSI	uart4_TX				gpio5.IO[11]
179	UART3_RTS	D4	ecspi1_SS0	uart3.RTS_B				gpio5.IO[9]
181	UART4_RXD	C6	uart4_RX	uart2.CTS_B	pcie1.CLKREQ_B			gpio5.IO[28]
183	UART4_TXD	B7	uart4_TX	uart2.RTS_B	pcie2.CLKREQ_B			gpio5.IO[29]
185	SYS_nRST							
187	NVCC_3V3							
189	NVCC_3V3							
191	VIN_4V2							
193	VIN_4V2							
195	VIN_4V2							
197	VIN_4V2							
199	VIN_4V2							
201	GND							
203	GND							

SODIMM Pin	Signal	i.MX8M Ball	Alt-0	Alt-1	Alt-2	Alt-3	Alt-4	Alt-5
2	GND							
4	MX8_ONOFF	W21						
6	USB1_SS_SEL	K19	rawnand.RE_B	gspl.A_DQS				gpio3.I0[15]
8	BOOT_MODE1	V6						
10	BOOT_MODE0	W6						
12	PCIe_nRST	J22	rawnand.DATA05	gspl.B_DATA[0]				gpio3.I0[11]
14	TCPC_nINT	F21	rawnand.CE2_B	gspl.A_SS1_B				gpio3.I0[9]
16	GPIO1_IO05	P7	gpio1.I0[5]	m4.NMI				ccmssrpgpmix.PMIC_READY
18	SD2_nRST	R22	usdhc2.RESET_B					gpio2.I0[19]
20	SD2_DATA2	P22	usdhc2.DATA2					gpio2.I0[17]
22	GND							
24	SD2_DATA1	N21	usdhc2.DATA1					gpio2.I0[16]
26	SD2_DATA0	N22	usdhc2.DATA0					gpio2.I0[15]
28	SD2_DATA3	P21	usdhc2.DATA3					gpio2.I0[18]
30	SD2_WP	M21	usdhc2.WP					gpio2.I0[20]
32	SD2_CMD	M22	usdhc2.CMD					gpio2.I0[14]
34	SD2_CLK	L22	usdhc2.CLK					gpio2.I0[13]
36	GPIO3_IO2	G21	rawnand.CE1_B	gspl.A_SS0_B				gpio3.I0[2]
38	BT_USB_D_N							
40	BT_USB_D_P							
42	CLKO2	J6	gpio1.I0[15]	usb2.OTG_OC				pwm4.OUT
44	GND							
46	GPIO1_IO12	L7	gpio1.I0[12]	usb1.OTG_PWR				sdma2.EXT_EVENT[1]
48	SPDIF_TX	F6	spdif1.OUT	pwm3.OUT				gpio5.I0[3]
50	SPDIF_RX	G6	spdif1.IN	pwm2.OUT				gpio5.I0[4]
52	CSI1_D2_N	C23						
54	CSI1_D2_P	B24						
56	CSI1_D1_P	D22						
58	CSI1_D1_N	C22						
60	CSI1_D3_P	D21						
62	CSI1_D3_N	C21						
64	CSI2_D0_P	D20						
66	CSI2_D0_N	C20						
68	CSI2_D3_P	D19						
70	CSI2_D3_N	C19						
72	GND							
74	GPIO1_IO13	K6	gpio1.I0[13]	usb1.OTG_OC				pwm2.OUT
76	SAI5_MCLK	K4	sai5.MCLK	sai1.TX_BCLK		coresight.TRACE_CLK		gpio3.I0[25]
78	SAI5_RXD3	K5	sai5.RX_DATA[3]	sai1.TX_DATA[5]	sai4.MCLK			gpio3.I0[24]
80	SAI5_RXD1	L4	sai5.RX_DATA[1]	sai1.TX_DATA[3]	sai1.TX_SYNC	sai5.TX_BCLK		gpio3.I0[22]
82	SAI5_RXC	L5	sai5.RX_BCLK	sai1.TX_DATA[1]				gpio3.I0[20]
84	I2C1_SDA	E8	i2c1.SDA	enet1.MDIO				gpio5.I0[15]
86	I2C1_SCL	E7	i2c1.SCL	enet1.1588_EVENT0_IN				gpio5.I0[16]
88	I2C3_SDA	E9	i2c3.SDA	pwm3.OUT	pcie1.CLKREQ_B			gpio5.I0[19]
90	SPDIF_EXT_CLK	E6	spdif1.EXT_CLK	pwm1.OUT				gpio5.I0[5]
92	PCIe1_nCLKREQ	F8	i2c4.SCL	pwm2.OUT	pcie2.CLKREQ_B			gpio5.I0[20]
94	I2C3_SCL	G8	i2c3.SCL	pwm4.OUT	gpt3.CLK			gpio5.I0[18]
96	GND							
98	SAI5_RXD2	M4	sai5.RX_DATA[2]	sai1.TX_DATA[4]	sai1.TX_SYNC	sai5.TX_DATA[0]		gpio3.I0[23]
100	SAI5_RXD0	M5	sai5.RX_DATA[0]	sai1.TX_DATA[2]	sai1.TX_SYNC	sai5.TX_SYNC		gpio3.I0[21]
102	GPIO1_IO08	N7	gpio1.I0[8]	enet1.1588_EVENT0_IN				usdhc2.RESET_B
104	SAI5_RXFS	N4	sai5.RX_SYNC	sai1.TX_DATA[0]				gpio3.I0[19]
106	HDMI_DDC_SCL	R3						
108	HDMI_DDC_SDA	P3						
110	HDMI_HPD	W2						
112	HDMI_CEC	W3						
114	HDMI_AUX_N	V2						
116	HDMI_AUX_P	V1						
118	HDMI_TX0_N	T2						
120	HDMI_TX0_P	T1						
122	HDMI_CLK_N	R1						
124	HDMI_CLK_P	R2						
126	HDMI_TX2_N	N1						
128	HDMI_TX2_P	N2						
130	HDMI_TX1_N	U1						
132	HDMI_TX1_P	U2						
134	GND							
136	LVDS0_TX0_N							
138	LVDS0_TX0_P							
140	LVDS0_TX1_N							
142	LVDS0_TX1_P							
144	LVDS0_TX2_N							
146	LVDS0_TX2_P							
148	LVDS0_CLK_N							
150	LVDS0_CLK_P							
152	LVDS0_TX3_N							
154	LVDS0_TX3_P							
156	SAI2_RXC	H3	sai2.RX_BCLK	sai5.TX_BCLK				gpio4.I0[22]
158	HEADPHONE_R							
160	HEADPHONE_L							
162	SAI2_MCLK	H5	sai2.MCLK	sai5.MCLK	sai5.RX_SYNC			gpio4.I0[27]
164	SPK_RP							
166	SPK_RN							
168	GND							
170	JTAG_TCK	T5						
172	JTAG_TMS	V5						
174	JTAG_TRST_B	U6						
176	JTAG_TDO	U5						
178	JTAG_TDI	W5						
180	GPIO1_IO01	T7						
182	GPIO1_IO03	P4						
184	CSI_nRST	N5	gpio1.I0[9]	enet1.1588_EVENT0_OUT				sdma2.EXT_EVENT[0]
186	GPIO5_IO2	D3	sai3.MCLK	pwm4.OUT				gpio5.I0[2]
188	NVCC_3V3							
190	NVCC_3V3							
192	VIN_4V2							
194	VIN_4V2							
196	VIN_4V2							
198	VIN_4V2							
200	VIN_4V2							
202	GND							
204	GND							

6. CPU Module interfaces

6.1 Display interfaces

i.MX8M-CM provides the following display interfaces:

- HDMI

i.MX8M-CM HDMI 2.0 interface is derived from the i.MX8M HD Display Transmitter Controller IP. The controller supports the following protocols:

- HDMI1.4, HDMI 2.0a support for resolution up to 4096x2160p60
- HDCP 2.2 and HDCP 1.4
- Pixel clock up to 596 MHz
- Display Port 1.3
- All standards share the same pins

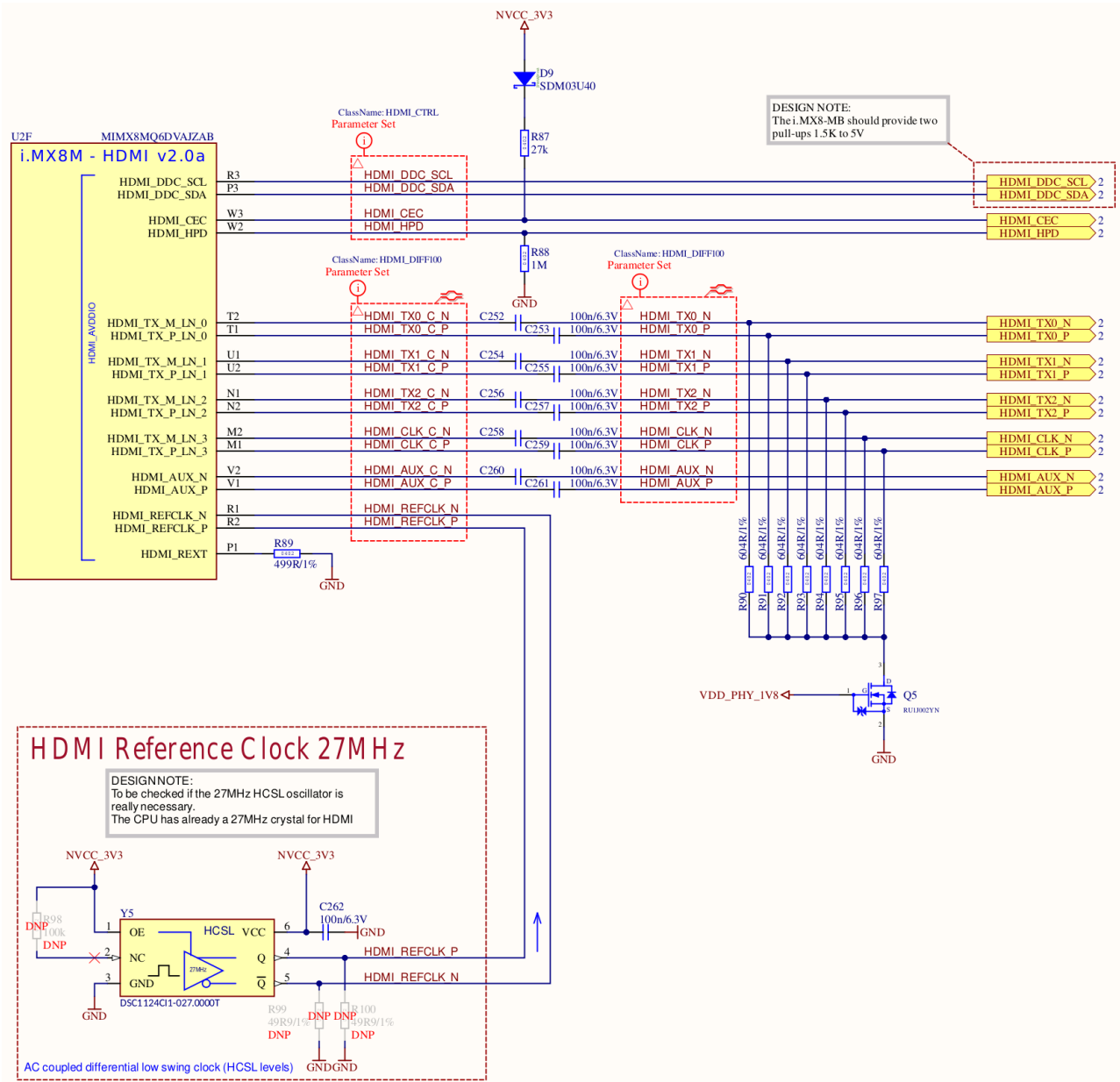


Figure 6.1:

- MIPI DSI

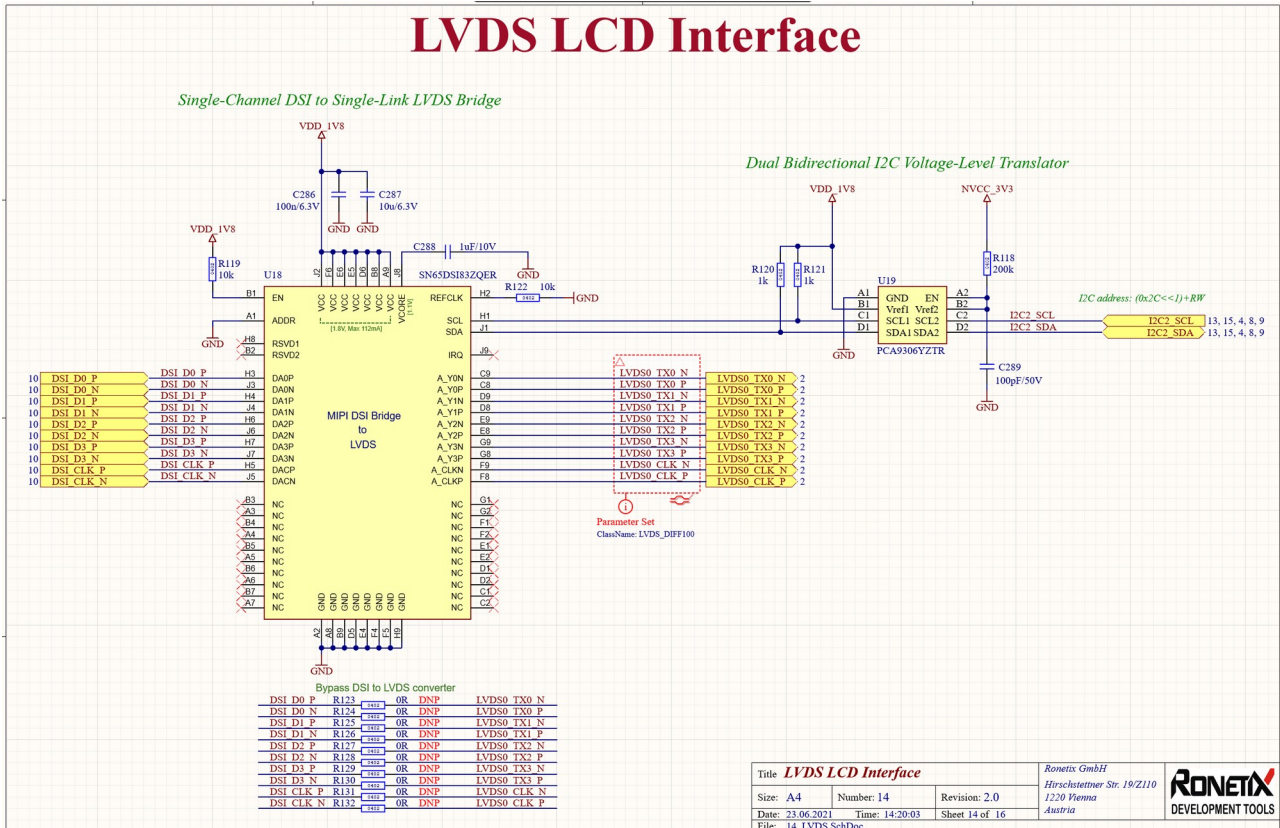
The MIPI-DSI interface is based on the four-lane MIPI display interface available with the iMX8M SoC. The DSI signals are available on the SODIMM204 connector if the SN65DSI83 is not assembled.

The following main features are supported:

- Up to 4 data lanes support D-PHY

- Implements all three DSI Layers (Pixel to Byte packing, Low Level Protocol, Lane Management)
 - Maximum resolution ranges up to FHD (1920 x 1080 @ 60 Hz)
 - Supports High Speed and Low Power operation
 - MIPI Alliance Specification for Display Serial Interface Version 1.1 compliant
-
- LVDS Interface (optional) – using Texas Instruments SN65DSI83 MIPI-DSI to LVDS bridge. If not assembled, then all DSI signals are available on the SODIMM204 connector. Texas Instruments SN65DSI83 supports following main features:
 - LVDS Output Clock Range of 25 MHz to 154MHz.
 - Suitable for up to 60 fps WUXGA 1920 x 1080 at 18 bpp and 24 bpp Color with Reduced Blanking
 - Capable of supporting the full resolution of the iMX8M MIPI-DSI interface with reduced blanking
 - ESD Rating ± 2 kV

LVDS LCD Interface



6.2 MIPI-CSI Camera interface

i.MX8M-CM MIPI-CSI interface is derived from the four-lane MIPI CSI1 host controller (MIPI_CSI1) integrated into the iMX8M SoC. The CSI1 host controller is a digital core that implements all protocol functions defined in the MIPI CSI-1 specification, providing an interface between CL-SOM-iMX8 and a MIPI CSI-1 compliant camera sensor. The following main features are supported:

- Up-to four data lanes and one clock lane.
- Maximum bit rate of 1.5 Gbps.
- Compliant with MIPI D-PHY standard specification V1.1 and Samsung D-PHY.
- Supports unidirectional Master operation
- Supports high speed mode (80Mbps - 1.5Gbps) per lane, providing 4K@30fps capability for the 4 lanes
- Support 5M pixel at 15 fps, 1080p30, 720p60, VGA at 60 fps

- Support for all CSI-2 data types:
 - RGB444, RGB555, RGB565, RGB666, RGB888
 - Legacy YUV420 8 bit
 - RAW6, RAW7, RAW8, RAW10, RAW12, RAW14
 - User Defined Data Types

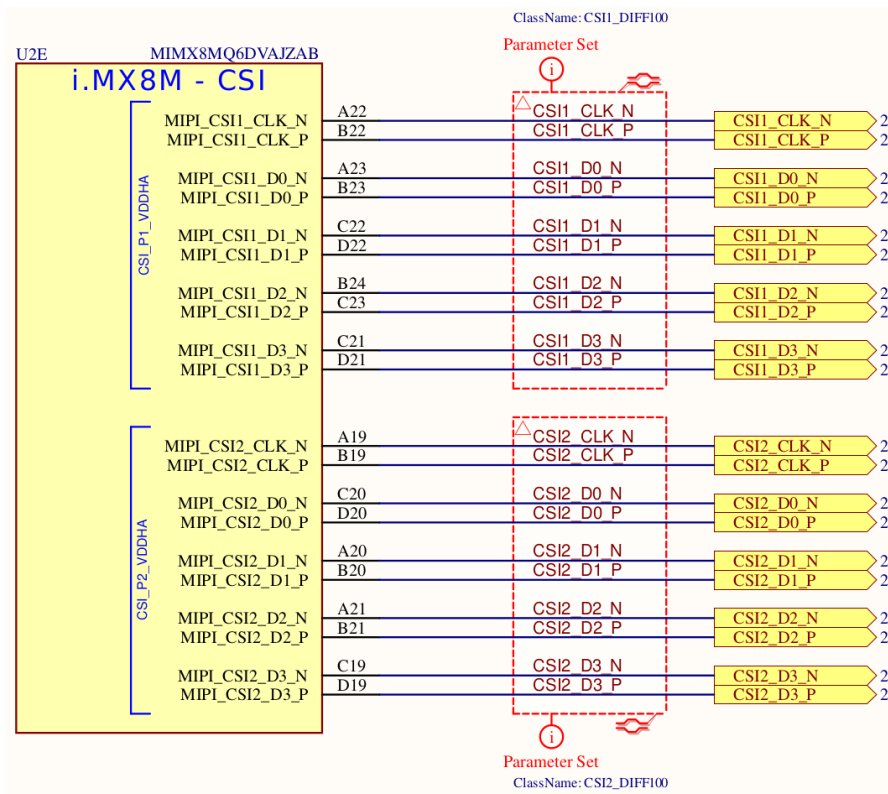


Figure 6.2: MIPI-CSI

Please refer to the i.MX8M Reference manual for additional details.

6.3 USB interface

The iMX8M SoC is equipped two USB controllers and PHYs that support USB 3.0 and USB 2.0. Each USB instance contains USB 3.0 core, which can operate in both 3.0 and 2.0 mode. One port supports dual-role functionality, while the second port is configured permanently for host mode. USB ports support the following main features:

- Complies with USB specification rev 3.0 (xHCI compatible)
- Can operate in both 3.0 and 2.0 mode
- 32 endpoints per slot

- Super-speed (5 Gbit/s), high-speed (480 Mbit/s), full-speed (12 Mbit/s), and low speed (1.5 Mbit/s) operations.
- Super-speed operation is not supported when OTG is enabled

Please refer to the i.MX8M Reference manual for additional details.

6.4 PCI-Express

The i.MX8M SoC is equipped with two single lane PCI Express port (PCIe) v2.1 ports.

On i.MX8M-CM SoM PCIe-1 is connected to the WiFi Module, but optionally can be routed to the SODIMM204 connector. PCIe-2 is available on the SODIMM204 connector and requires an external PCIe clock.

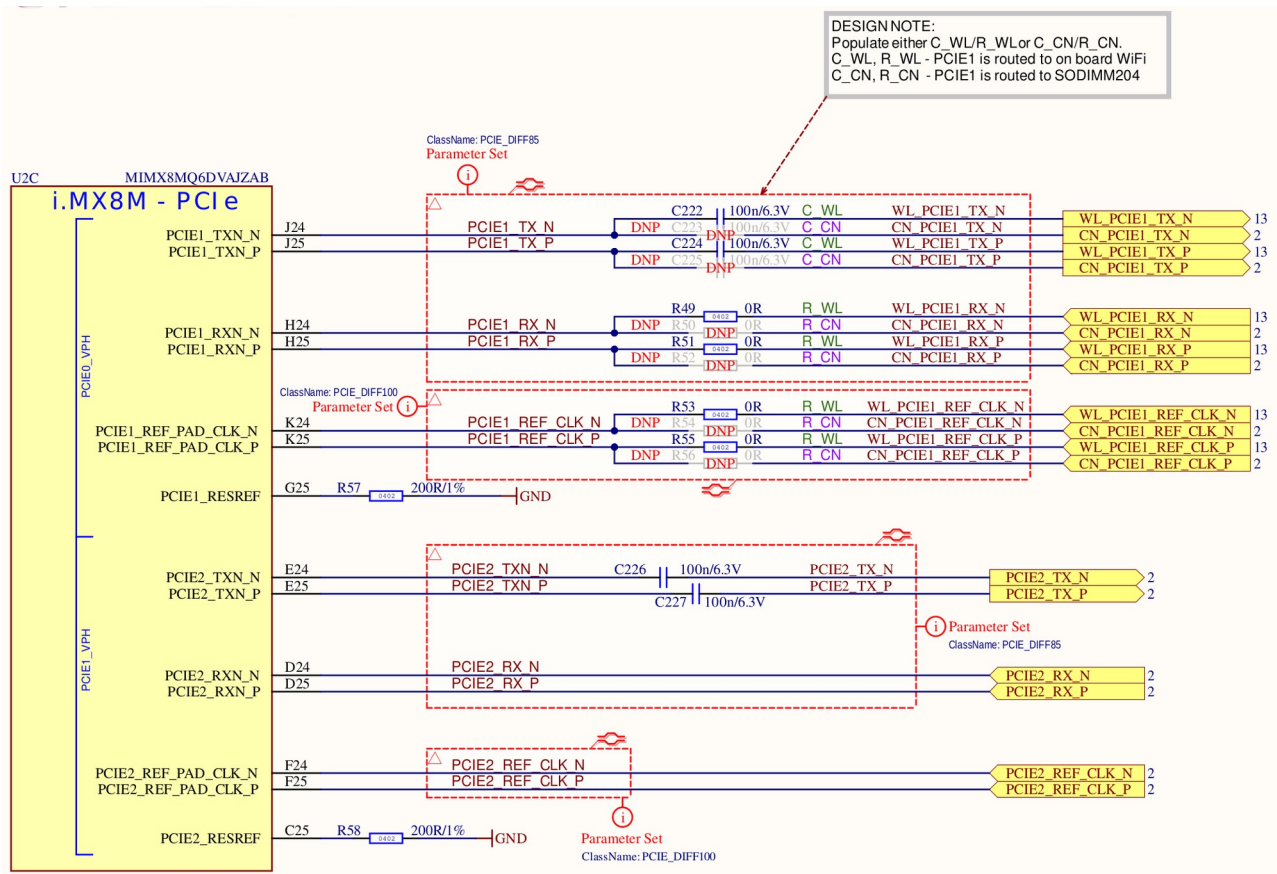


Figure 6.3: PCIe

The PCI Express ports support the following main features:

- Single lane compliant with PCI Express base specification v2.1 (6.0Gbps)

- Dual mode operation to function as root complex or endpoint
- Port solution includes the controller, an analog PHY macro, and application logic to source and sink data

Please refer to the i.MX8M Reference manual for additional details.

6.5 MMC, SD, SDIO

The i.MX8M SoC is equipped with two MMC/SD/SDIO controller IPs (uSDHC). On i.MX8M-CM SD1 is connected to the eMMC. SD2 is available on the SODIMM204 connector.

The uSDHC supports the following main features:

- Fully compliant with MMC command/response sets and physical layer as defined in the multimedia card system specification, v5.0/v4.4/v4.41/v4.4/v4.3/v4.2.
- Fully compliant with SD command/response sets and physical layer as defined in the SD memory card specifications, v3.0 including high-capacity SDXC cards up to 2 TB.
- 1-bit or 4-bit transfer mode specifications for SD and SDIO cards up to UHS-I SDR104 mode (104 MB/s max).
- Dedicated “card detection” and “write protection” signals
- Both 1.8V and 3.3V signaling support (uSDHC port 1 with 1-bit and 4-bit operation modes only).

Please refer to the i.MX8M Reference manual for additional details.

6.6 UART

The i.MX8M-CM exposes up to 4 UART interfaces some of which are multiplexed with other peripherals.

The i.MX8M UARTv2 supports the following features:

- High-speed TIA/EIA-232-F compatible.
- 7- or 8-bit data words, 1 or 2 stop bits, programmable parity (even, odd or none).
- Programmable baud rates up to 4 Mbps.
- 32-byte FIFO on Tx and 32 half-word FIFO on Rx supporting auto-baud.
- Serial IR interface low-speed, IrDA-compatible (up to 115.2 Kbit/s).
- Hardware flow control support for request to send and clear to send signals.

- RS-485 driver direction control.
- DCE/DTE capability.
- RX_DATA input and TX_DATA output can be inverted respectively in RS-232/RS-485 mode.
- Various asynchronous wake mechanisms with capability to wake the processor from STOP mode through an on-chip interrupt.

Please refer to the i.MX8M Reference manual for additional details.

6.7 I2C

The i.MX8M SoC is equipped with three I2C bus interfaces. I2C1 and I2C3 are available on the SODIMM204 connector. I2C2 is used internally, not available on SODIMM204. The following general features are supported by all I2C bus interfaces:

- Compliant with Philips I2C specification version 2.1
- Supports standard mode (up to 100K bits/s) and fast mode (up to 400K bits/s)
- Multimaster operation
- Master or Slave operation mode.

I2C usage table:

I2C USAGE AND ADDRESS TABLE		
NAME	PERIPHERAL	ADDRESS
I2C1	i.MX8-MB: USB3.0 Power Switch	(0x050<<1)+RW
	i.MX8-MB: RTC clock	(0x051<<1)+RW
	i.MX8-MB: miniPCIe Ref. Clock	(0x6A<<1)+RW
	i.MX8-MB: Camera on CSI1	(0x3C<<1)+RW
I2C2 only on CM	i.MX8-CM: PMIC control	(0x4B<<1)+RW
	i.MX8-CM: WiFi Ref. Clock	(0x68<<1)+RW
	i.MX8-CM: EEPROM	(0x50<<1)+RW
	i.MX8-CM: Audio Codec	(0x1A<<1)+RW
	i.MX8-CM: LVDS	(0x2C<<1)+RW
I2C3	i.MX8-MB: mPCIe connector	
	i.MX8-MB: Camera on CSI2	(0x3C<<1)+RW

Figure 6.4: I2C usage

6.8 SPI

Up-to three SPI interfaces are accessible through the i.MX8M-CM base board interface. The SPI interfaces are derived from i.MX8M integrated synchronous serial interface (eCSPI). Each instance of eCSPI port can operate as either a master or as an SPI slave. The following features are supported:

- Data rate up to 52 Mbit/s.
- Full-duplex synchronous serial interface.
- Master/Slave configurable.
- Up-to four chip select signals to support multiple peripherals.
- Transfer continuation function allows unlimited length data transfers.
- 32-bit wide by 64-entry FIFO for both transmit and receive data.
- Polarity and phase of the Chip Select (SS) and SPI Clock (SCLK) are configurable.
- Direct Memory Access (DMA) support.

Please refer to the i.MX8M Reference manual for additional details.

6.9 Quad SPI

QSPI-A is connected onboard to a QSPI NOR Flash. QSPI.B is not available on SODIMM204.

The following features are supported by the QSPI controller:

- Flexible sequence engine to support various flash vendor devices.
- Single pad, dual pad or quad pad mode of operation.
- Single data rate/double data rate mode of operation.
- DMA support.
- Memory mapped read access to connected flash devices.
- Multi-master access with priority and flexible and configurable buffer for each master.

Please refer to the i.MX8M Reference manual for additional details.

6.10 PWM

Up to four PWM output signals are available at the i.MX8M-CM base board interface. The following key features are supported:

- 16-bit up-counter with clock source selection
- 4 x 16 FIFO to minimize interrupt overhead
- 12-bit prescaler for division of clock
- Sound and melody generation
- Active high or active low configured output
- Interrupts at compare and rollover

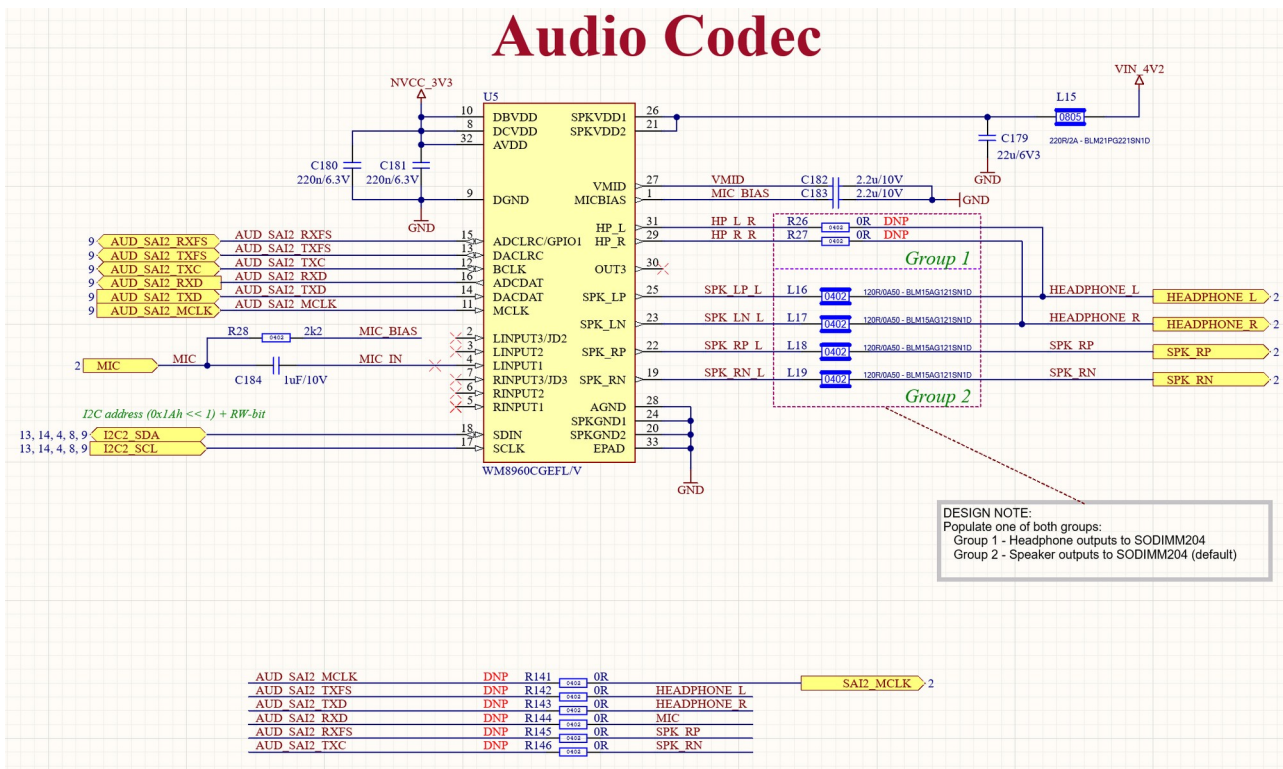
Please refer to the i.MX8M Reference manual for additional details.

6.11 Analog Audio

i.MX8M-CM analog audio functionality is implemented by the Wolfson WM8960 audio code. WM8960 is connected to I.MX8M SAI2 port.

Please refer to the WM8960 datasheet for additional details.

If the WM8960 is not populated, the SAI signals can be bypassed to the SODIMM204 connector. Either the speaker or the headphone signals can be provided to the SODIMM204 connector.



6.12 GPIO

Up-to 7 of the i.MX8M general purpose input/output (GPIO) signals are available on the SODIMM204 connector. When configured as an output, it is possible to write to an i.MX8M register to control the state driven on the output pin. When configured as an input, it is possible to detect the state of the input by reading the state of an i.MX8M register. In addition GPIOs peripheral can produce interrupts.

6.13 JTAG

The System JTAG Controller (SJC) provides debug and test control with maximum security. The test access port (TAP) is designed to support features compatible with the IEEE standard 1149.1 v2001 (JTAG). Support IEEE P1149.6 extensions to the JTAG standard are for AC testing of selected IO signals. The JTAG signals are available on the SODIMM204 connector.

7. Power Supply

7.1 Power supply from base board

i.MX8M-CM is powered by regulated DC supply 3.8-5.0V

Signal	Type	Description
VIN_4V2	Power input	Main Power Supply 3.8-5.0V
GND	Power input	Common ground

7.2 Power supply provided to base board

i.MX8M-CM provides a 3.3V power supply to the SODIMM204 connector.

Signal	Type	Description
NVCC_3V3	Power output	3.3V, Max. 1.5A

7.3 System Signals

Signal	Type	Description
MX8_ONOFF	Input with Pull-Up resistor	ON/OFF button input (De-bouncing provided at this input). Short connection to GND in OFF mode causes internal power management state machine to change state to ON. In ON mode short connection to GND generates interrupt (intended to SW controllable power down). Long above ~5s connection to GND causes “forced” OFF.
SYS_nRST	Input	PMIC Power On signal

8. Electrical Specifications

8.1 Absolute maximum ratings

Parameter	Min	Max	Unit
VIN_4V2 – Main Power Supply	-0.3	5.25	V
USB_VBUS - USB_HOST_VBUS, USB_OTG_VBUS	-0.3	5.25	V

8.2 Recommended Operating Conditions

Parameter	Min	Typ	Max	Unit
VIN_4V2 – Main Power Supply	3.8	4.2	5.0	V
VIN_4V2 – recommended source capability		4.0		A

9. Operating Temperature Ranges

Range	Temp.
Commercial	0° to +70°C
Industrial	-40° to +85°C

10. Cooling

A cooling solution must be provided to ensure that under worst-case conditions the temperature on any spot of the heat-spreader surface is maintained according to the iMX8M-CM temperature specifications.

11. Mechanical Drawings

All dimensions are in millimeters.

The height of all parts is < 2mm.

The base board connector provides 2.8mm board to board clearance.

Board thickness is 1.0mm

11.1 Base board mounting

i.MX8M-CM SoM has two mounting holes for mounting to the base board which are plated and connected to GND.

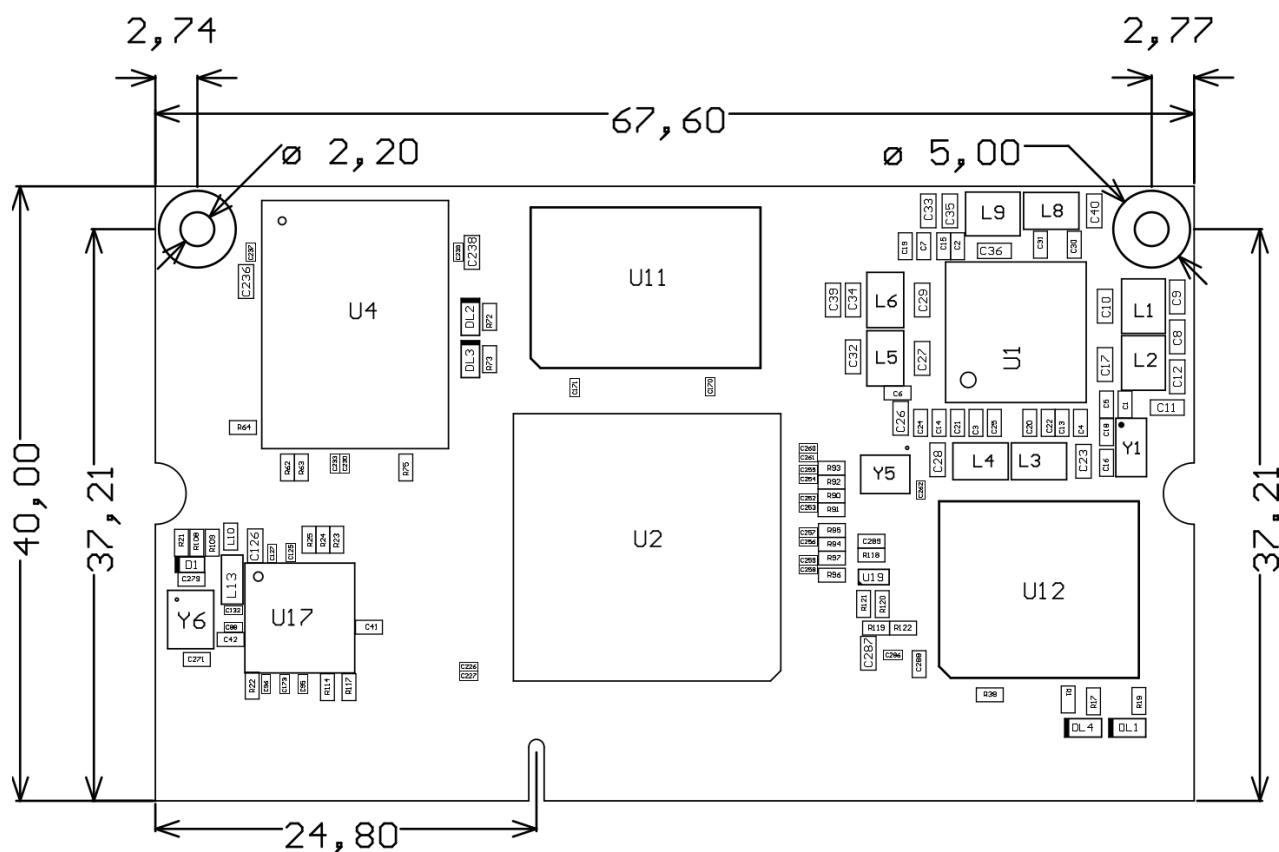


Figure 11.1: Mechanical drawing

11.2 Standoffs

Fix i.MX8M-CM to the base board by mounting two spacers with suitable screws. The spacers should be:

- M2x0.4, length 3.0mm

12. Warranty Terms

Ronetix guarantees hardware products against defects in workmanship and material for a period of one (1) year from the date of shipment. Your sole remedy and Ronetix's sole liability shall be for Ronetix, at its sole discretion, to either repair or replace the defective hardware product at no charge or to refund the purchase price. Shipment costs in both directions are the responsibility of the customer. This warranty is void if the hardware product has been altered or damaged by accident, misuse or abuse.

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